



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**Notification# 20220802002.0  
Datasheet for SN74LVC1G3157  
Information Only**

**Date:** August 22, 2022  
**To:** TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team ([PCN ww admin team@list.ti.com](mailto:PCN_admin_team@list.ti.com)).

Sincerely,

PCN Team  
SC Business Services


**Information Only  
Attachments**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
SN74LVC1G3157DCKR	null
SN74LVC1G3157YZPR	null
SN74LVC1G3157DBVR	null
SN74LVC1G3157DCK3	null
SN74LVC1G3157DRYR	null
SN74LVC1G3157DRLR	null
SN74LVC1G3157DSFR	null

Technical details of this Product Change follow on the next page(s).

<b>Notification Number:</b>	20220802002.0	<b>Notification Date:</b>	August 22, 2022
<b>Title:</b>	Datasheet for SN74LVC1G3157		
<b>Customer Contact:</b>	PCN Manager	<b>Dept:</b>	Quality Services
<b>Change Type:</b>			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	
<b>Notification Details</b>			
<b>Description of Change:</b>			
<p>Texas Instruments Incorporated is announcing an information only notification.  The product datasheet(s) is being updated as summarized below.  The following change history provides further details.</p>			
<div style="display: flex; justify-content: space-between; align-items: center;">  <div style="text-align: right;"> <b>SN74LVC1G3157</b>  <small>SCES424M – JANUARY 2003 – REVISED AUGUST 2022</small> </div> </div>			
<b>Changes from Revision L (May 2017) to Revision M (August 2022)</b>			<b>Page</b>
• Updated the numbering format for tables, figures, and cross-references throughout the document.....			1
• Updated the <i>Pin Configuration and Functions</i> section.....			4
• Updated the equation in the <i>Detailed Design Procedure</i> section.....			18
The datasheet number will be changing.			
Device Family	Change From:	Change To:	
SN74LVC1G3157	SCES424L	SCES424M	
These changes may be reviewed at the datasheet links provided. <a href="https://www.ti.com/product/SN74LVC1G3157">https://www.ti.com/product/SN74LVC1G3157</a>			
<b>Error! Bookmark not defined.</b>			
<b>Reason for Change:</b>			
To accurately reflect device characteristics.			
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
<b>Changes to product identification resulting from this notification:</b>			
None.			
<b>Product Affected:</b>			
74LVC1G3157DBVRE4	74LVC1G3157DRYRG4	SN74LVC1G3157DRLR	SN74LVC1G3157DTBR
74LVC1G3157DBVRG4	SN74LVC1G3157DBVR	SN74LVC1G3157DRY2	SN74LVC1G3157YZPR
74LVC1G3157DCKRE4	SN74LVC1G3157DCK3	SN74LVC1G3157DRYR	SN74LVC1G3157YZTR
74LVC1G3157DCKRG4	SN74LVC1G3157DCKR	SN74LVC1G3157DSFR	

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

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